



Recent Advances in Soft Robotics and Flexible Electronics: From Materials to Applications

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Message from the Guest Editors

Dear Colleagues,

In recent years, soft robotics and flexible electronics have been drawing significant attention from many different fields ranging from actuators, healthcare, wearables, human-machine interfaces, and sensors and as they can provide new solutions that were not possible with traditional rigid robotics and electronics such as dexterity, miniaturization, wearability, multi-functionality, and deformability. Furthermore, lightweight, soft, and flexible electronics often offer conformal contact with the human body for reliable, accurate, and portable health monitoring or diagnosis in real time. However, to develop such unusual forms of robotics and electronics, advanced interdisciplinary studies and experiments involving biology, chemistry, material sciences, mechanics, and electronics are essential. This Special Issue covers a broad range of topics on recent advancements in the field of soft robotics and flexible electronics from their novel materials, design, manufacturing techniques, and strategies in designing soft/flexible mechanisms to their practical applications.





Editor-in-Chief

Message from the Editor-in-Chief

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